# TK PASTE

Conductive bonding
for grounding and shielding

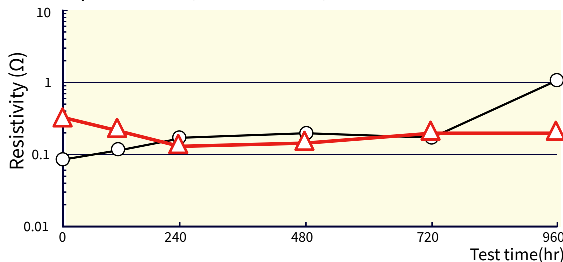
# 80°C curing conductive adhesive

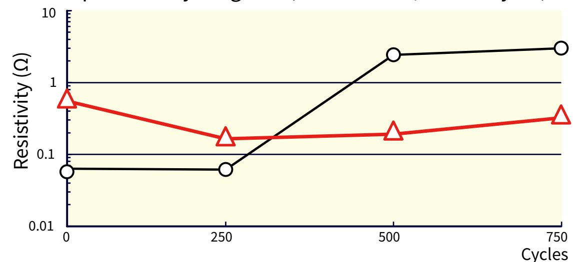
## CR-5930

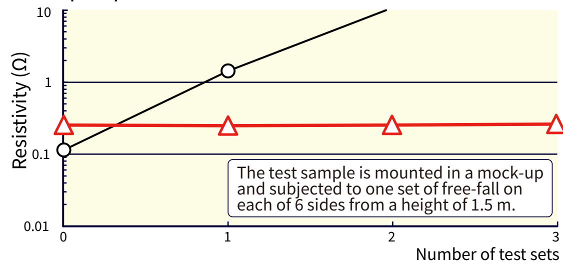
**Low temp. curing** | **Impact resistance** | **Solventless**

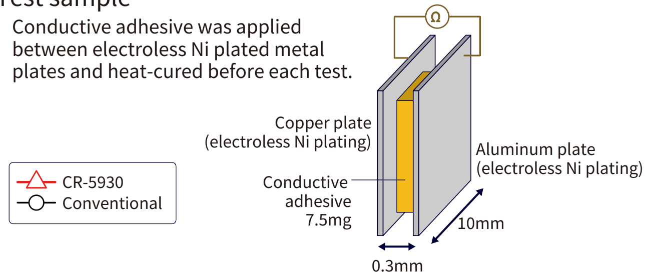
## Possible applications

*Grounding of camera modules (shielded CAN)
*Grounding of various sensors without heat resistance
*Conductive bonding of wearable devices and film devices, etc.



Apply with dispenser

| | CR-5930 |
|---|---|
| Conductive filler | Silver |
| Binder | Epoxy (single-component / solventless) |
| Curing condition | 80°C×60min or 120°C×10min |
| Specific resistivity | $2\times10^{-2}$ Ω·cm |
| Viscosity (@25°C, 5rpm) | 25Pa·S |
| Storage condition | -10°C or lower |

The data in this catalog is provided as typical examples and may not apply to all applications and conditions.